

VT-45

Datasheet

High Tg Material

VT-45TC/Laminate VT-45PP/Prepreg

General Information

- High Tg FR-4 (Tg>170)
- Dicy Cured System
- UV Blocking;
- Laser Fluorescing;

Application

For Single Side\Double Side\Multilayer PWB Applications

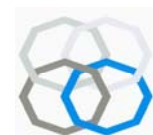
Availability

VT-45TC Laminates are available in thickness from .002" to .200" and with the copper foil from 1/4oz to 12oz; Ventec can supply either reverse treated (RT) or double side treated copper foil. On cores $\leq .005$ ", it is recommended to use the reverse treated copper due to the low profile. The peel strength for RT foil is $\approx 1-2$ lbs/in (0.35Kg/m) less than Standard foil.

VT-45PP pre-pregs are available in many E-Glass styles, such as 7628, 7629, 1506, 1500, 2113, 2313, 3313, 2116, 1080, 1086, 1078, 106 & 1067.

Storage Condition & Shelf Life

		Prepreg		Laminate
Storage	Temperature	Below 22°C(73°F)	Below 5°C(41°F)	Below 22°C(73°F)
Condition	Relative Humidity	Below 55%RH	/	Below 55%RH
Shelf Life		3 Month	6 Month	12Month(airproof)



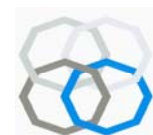
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Properties Sheet: IPC-4101B Specification Sheet(s)/21, 24, 26

(Test Sample: .036"1/1)

TEST ITEM		Test Condition (IPC-TM-650 or As Noted)	UNIT	Specification (IPC-4101 B)	Typical Value	
					VT-45	Normal FR-4
Flexural Strength	Warp	2.4.4	MPa	>415	560	600
	Fill			>345	450	500
Peel Strength (1 oz)	As Receive	2.4.8	1b/in	8.0 min	9.34	8.59
	After Thermal				9.13	8.03
Glass Transition Temp.(Tg),DSC		2.4.25	℃	-	175-185	136-140
Decomposition Temp. (Td) TGA		ASTM D3850	℃	-	290	290~310
Z-axis C.T.E.	Before Tg	TMA	in/in/ ℃	60x10 ⁻⁶	45x10 ⁻⁶	50x10 ⁻⁶
	After Tg			300x10 ⁻⁶	220x10 ⁻⁶	250x10 ⁻⁶
Moisture Absorption	D-24/23	2.6.21	%	0.35 max	0.25	0.15
	After PCT	1atm.,121℃, 1hour	%	-	0.36	0.28
Volume Resistance	After Moisture	2.5.17.1	MΩ-cm	≥ 106	5×10 ⁸	5×10 ⁸
	E-24/125			≥ 103	5×10 ⁶	5×10 ⁶
Surface Resistance	After Moisture	2.5.17.1	MΩ	≥ 104	5×10 ⁷	5×10 ⁷
	E-24/125			≥ 103	5×10 ⁶	5×10 ⁶
Electric Strength		2.5.6.2	KV/mm	≥30	54	54
Dielectric Constant (Dk)	250 MHz	2.5.3,2.5.9,2.5.5	-	5.4 max	4.42	4.42
	750 MHz				4.39	4.39
	1.0 GHz				4.38	4.38
	2.0 GHz				4.36	4.36
Dispersion Factor (Df)	250 MHz	2.5.3,2.5.9,2.5.5	-	0.035 max	0.022	0.022
	750 MHz				0.021	0.021
	1.0 GHz				0.021	0.021
	2.0 GHz				0.020	0.020
Thermal Stress	288℃,Sold Dip	2.4.13.1	Sec.	60 Sec.	>300	90-120
Pressure Cook Test		15psi/30min/ 288℃/10sec.	Cycle	2 cycles min	5 - 8	6-8
T260		2.4.24.1	Min	>30	10~15	18
Flame Resistance		UL94	-	V1	V0	V0
Comparative Tracking Index (CTI)		UL-7461 ASTM D3638	Voltage	—	175~250 (Grade 3)	175~250 (Grade 3)

※All test data provided are typical values and are not intended to be specification values.



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Process Guideline

Press Condition

1. Heating rate(Rise of Rate) of material:
Programmable Press: 1.5-3.0°C/min (3~5°F/min). Manual Press:3~6°C /min (5~10°F/min)
2. Curing Temperature & Time: >50min at more than 180°C (356°F)[Material Temperature].
3. Full Pressure: ≥250-300psi
4. Vacuuming should be continued until **over 140°C** (284°F) [Material Temperature]

Typical Drilling Parameters (φ0.3-1.0 mm)

1. Spindle Speed:	64-105	KRPM
2. Feed Rate:	100-150	Inch / min
3. Retract Rate:	596-600	Inch / min
4. Chip Load:	0.7~2.0	mil / Rev.

Desmearing Process

Desmear rate of **VT-45** is less that of the conventional FR-4;
Minor adjustments to the desmear process may be necessary for the higher Tg materials.
Check with your chemical supplier for recommendations.